ELECTRONICS CO., LTD,

SPECIFICATION

 TITLE
 SPC. NO.
 PAGE: 1 OF 5

 DIN CONNECTOR
 HDC-052
 DATE: 2003.09.09

SPECIFICATION

1. Standard atmospheric condition:

Unless otherwise specified, the standard range of atmospheric conditions for making

measurements and tests are as follows:

Ambient temperature: $5^{\circ}\mathbb{C}$ to $35^{\circ}\mathbb{C}$ Relative humidity : 45% to 85%Air pressure : 86kPa to 106kPa

If there is any doubt about the results, measurements shall be made within the following limits:

Ambient temperature: $20\pm2^{\circ}$ C

Relative humidity : 60% to 70%

Air pressure : 86kPa to 106kPa

Operating temperature range: -20° C to 70° C Storage temperature range: -40° C to 70° C

2. Electrical characteristics

	Item	Condition	Specifications
	Rated voltage/		AC 100V 1A
1	Rated current		or
	Kateu current		DC 12V 2A
	Insulation	A voltage of 500V D.C. shall be applied for 1 min.	
2	resistance	between mutually insulated metal parts after which	$100 \mathrm{M}\Omega$ MIN.
	resistance	measurement shall be made.	
2	Contact	Measurement shall be made at with small current	30 mΩ MAX.
3	resistance	1000 Hz (100mA MAX.)	30 III 22 IVIAA.
1	Dielectric	500V A.C. r.m.s (50 Hz to 60 Hz) for 1 min.	Without damage to parts, arcing
4	strength	Trip current: 1mA	or breakdown, etc.

ISSUE	DATE	WRTN	СНКО	APVD	DESCRIPTIONS
	2003.09.09	陳樹民	龔雲輝	龔雲輝	
∆ x 3	2008.04.22	黃健瑋	夏正雄	郭遠峰	Modify the item 4.4 and 4.5 and 4.7
∆ x3	2013.01.18	李阮龍	郭素玲	郭遠峰	Modify the item 4.4 Add the item 6 \ 8
∆ x 0	2013.11.20	李阮龍	郭素玲	郭遠峰	Delete the factory address (P.4)

ELECTRONICS CO., LTD,

SPECIFICATION

TITLE	SPC. NO.	PAGE:	2 OF 5
DIN CONNECTOR	HDC-052	DATE:	2003.09.09

3. Mechanical characteristics

	Item	Condition	Specifications			
1	Operating force	The insertion force and the withdrawal force shall be measured with the mating plug.				
		Insertion force	34.3N (3.5kgf) MAX.			
		Withdrawal force	4.9N to 29.4N (0.5kgf to 3.0kgf)			
2	Withstanding force	It shall be measured with the gauge of $\ \phi$ 1.46+0/-0.1.	0.83N (85gf) MIN			

4. Endurance characteristics

	T. Eliquiance characteristics							
	Item	Condition	Specifications					
1	Operating endurance	The life test shall consist of 1000 cycles of insertion and withdrawal with mating plug covered with a thin coat of grease in order to prevent from heating or wearing, at a rate of 10 to 20cycles per minutes under no load.	Electrical and mechanical characteristics shall be satisfied.					
		Contact resistance	50 mΩ MAX.					
		Insulation resistance	$10 \mathrm{M}\Omega$ MIN.					
		Insertion force	39.2N (4kgf) MAX.					
2	Humidity test	Temperature : 40°C±3°C Relative humidity : 90% ±5% for 96 hours. The testing jack shall be left alone for 1∼2 hours in a room ambient for removing dewdrops, after measurement shall be made.	Electrical and mechanical characteristics shall be satisfied.					
		Insulation resistance	$10\mathrm{M}\Omega$ MIN.					
3	Dry heat	The pin jack shall be subjected to temperature of $70^{\circ}\text{C}\pm3^{\circ}\text{C}$ for a period of 96 hours, then shall be allowed to remain in room ambient conditions for $1\sim2$ hours. After test, there shall be no abnormality appearance.	Electrical and mechanical characteristics shall be satisfied.					

ELECTRONICS CO., LTD,

SPECIFICATION

TITLE	SPC. NO.	PAGE:	3 OF 5
DIN CONNECTOR	HDC-052	DATE:	2003.09.09

	Item	n Condition			Specifications		
		Wave soldering Process	Wave soldering Process				
		Profile Feature	Pb-Free A	Assembly			
			Topside PCB Padside PCB				
		Preheat -Temperature min -Temperature max -Time (ts min to max)	120°C (Ts1 max)	110°C (Ts min) 150°C (Ts max) 75 sec	Electrical and mechanical characteristics shall be satisfied,		
		Peak/Classification	165°C	260°C ±5°C	and not show remarkable		
		Temperature 7°C 2	(Tp1)	(Tp)	failure.		
		Time within 5°C of		10 sec (within 2 times every			
	\triangle	actual Temperature (tp)		time 2-3 sec)			
		Time 25°C to Peak temperature		3 minutes max			
		Wave Soldering Temper	erature Profile a	re as below			
		⚠ About the plastic pr		ata sheet of plastic.			
4	Resistance to Soldering Heat Test	Temperature			tp		
		Ts max Ts min			Tp1 max TS1 max		
		0			Time		
			-	— ts —	-		
		Topside PCB					
			_				
			_	side PCB	I		
		Soldering Iron Test Temperature of soldering time: 3±1 so	—— Pad	side PCB	Same as Wave soldering Process		
		Temperature of soldering soldering time: 3±1 so	—— Pad	side PCB	Same as Wave soldering Process 34.3N (3.5kgf) MAX.		

ELECTRONICS CO., LTD,

SPECIFICATION

TITLE	SPC. NO.	PAGE:	4 OF 5
DIN CONNECTOR	HDC-052	DATE:	2003.09.09

	Item	Condition Specifications							
5	Solderability	Temperature of solder : $\triangle 250^{\circ}$ C $\pm 5^{\circ}$ C The soldered area shall be covered a minimum of 90% of							
		Length of dip: 2 ±0.5mm (from top of terminal) the surface being immersed.							
6	Resistance to soldering flux	The terminals of DIN connector mounted on a printed Electrical and mechanical circuit board(t=1.6 mm)shall bedipped into soldering characteristics shall be satisfied, flux of GX-7(ASAHI CHEMICALS)or equivalent to the contact area will then have preflux, and shall be immersed into molted solder. no soldering flux left.							
7	Composite temperature / humidity cyclic test	The jack board shall be subjected to 5 cycles. Then jack board shall be stored at standard atmospheric conditions for 30 minutes, after which measurement shall be made. Dimensional requirements electrical and mechanical characteristics shall be satisfied.							

≜6. Soldering condition shelf life about 6 months depend on storage condition of humidity, temperature and others factors.

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SPECIFICATION

 TITLE
 SPC. NO.
 PAGE: 5 OF 5

 DIN CONNECTOR
 HDC-052
 DATE: 2003.09.09

Test group		Sample group								
NO.	NO. Test item		В	С	D	Е	F	G	Н	I
2.2	Insulation resistance	1		1,6	1,6	1,6	1,6	1,6		1,6
2.3	Contact resistance	2		2,7	2,7	2,7	2,7	2,7		2,7
2.4	Dielectric strength	3		3	3	3	3	3		3,8
3.1	Operating force	4		4,8	4,8	4,8	4,8	4,8		4,9
3.2	Withstanding force		1							
4.1	Operating endurance			5						
4.2	Humidity Test				5					
4.3	Dry heat					5				
4.4	Resistance to Soldering Heat Test						5			
4.5	Solderability Test							5		
4.6	Resistance to soldering flux								1	
4.7	Composite temperature / humidity cyclic test									5

Test sample quality: 2 pcs / group